Momentive's Thermal Interface Materials

Product Guide

Application	Performance Characteristics	Solutions
Thermal interface in high performance devices and semiconductor packages as TIM1 interfaces or TIM2 thermal paths to heat sinks	• Wide operating temperatures • Repairability • Low thermal resistance • Minimal ionic impurities • Thin bond lines	TIG830SP 4.1 W/m.K TIG400BX 4.0 W/m.K TIG300BX 3.0 W/m.K TIG210BX 2.1 W/m.K
	• Structural adhesion • Minimal ionic impurities • Low thermal resistance • Thin bond lines • Wide operating temperatures	TIA600R 6.0 W/m.K TIA350R 3.5 W/m.K TIA260R 2.6 W/m.K XE13-C1862PT 2.5 W/m.K
Thermal management for optical pick-ups, automotive control units and power supplies	• Structural adhesion • Low thermal resistance • Room temperature cure	TIA0260 2.6 W/m.K TIA0220 2.2 W/m.K
	• Non-adhesive, repairable • Low thermal resistance • Room temperature cure	TIS380CM 3.6 W/m.K TIS420C 4.2 W/m.K
Thermal interface with heat dissipation devices in control units, medium performance chip sets etc.	• Moderate thermal conductivity • Wide operating temperatures	TIG1000 1.0 W/m.K TIG2000 2.0 W/m.K
	• Moderate thermal conductivity • Structural adhesion • Low thermal resistance	TSE3281-G 1.7 W/m.K TSE3280-G 0.9 W/m.K
Board level and power supply component assembly	• Moderate thermal conductivity • Structural adhesion • Low thermal resistance • Room temperature cure	TIA0260 2.6 W/m.K TIA0220 2.2 W/m.K XE11-B5320 1.3 W/m.K
Rubber and Gel potting / encapsulation in power modules, converters, IGBT units.	• Good thermal conductivity • Low ~ moderate viscosities • Stress relief • Handling and cure benefits • Repairability	TIA222G 2.2 W/m.K TIA221G 2.1 W/m.K TIA216G 1.6 W/m.K

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